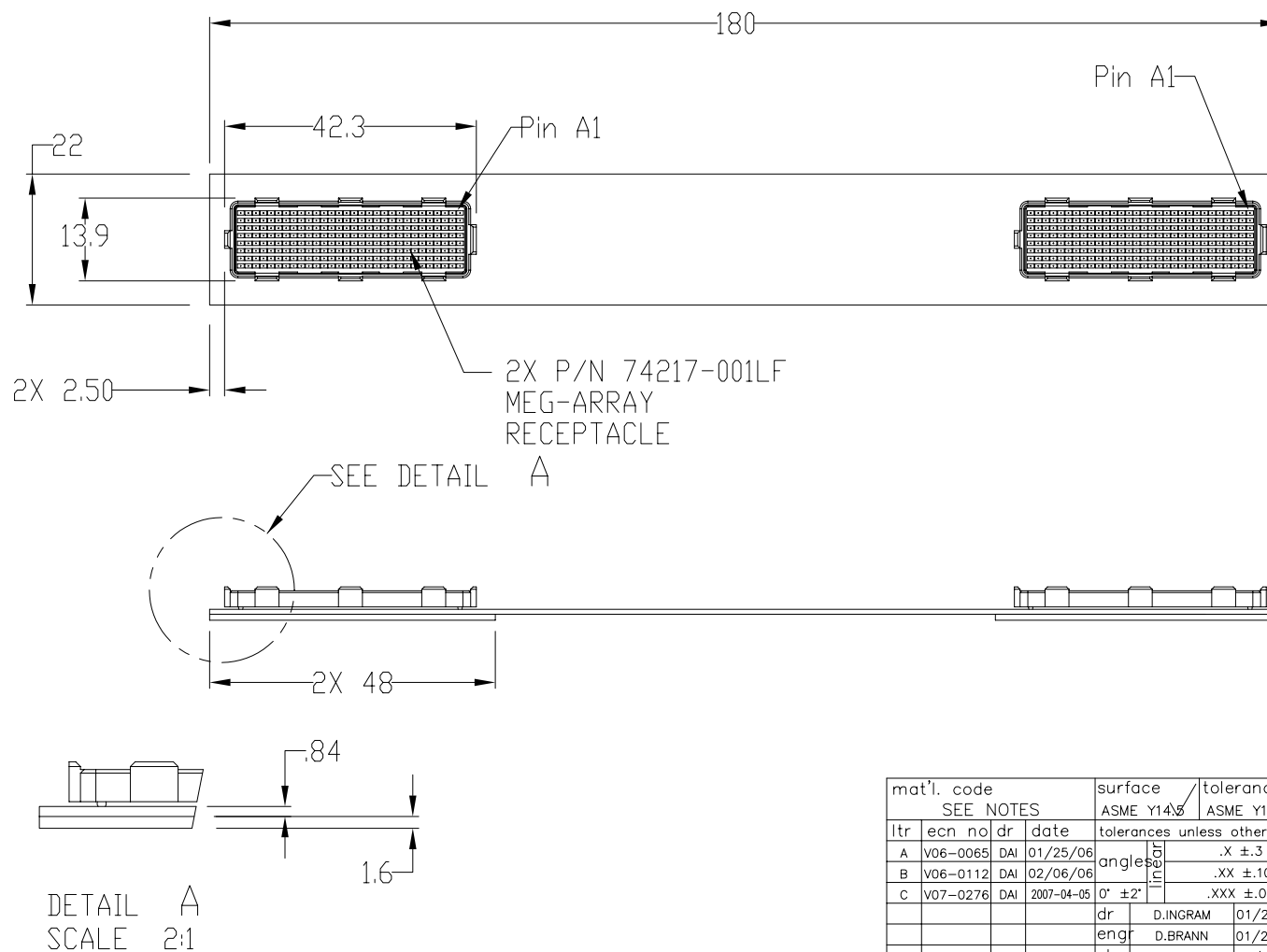


PRODUCT NUMBER

10061262-001LF



mat'l. code				surface		tolerance	projection	product family	
SEE NOTES				ASME Y14.5		ASME Y14.5	specified	title	
ltr	ecn no	dr	date	tolerances unless otherwise		angle	MM	FLEX CIRCUIT W/240 POS. MEG-ARRAY RECEPTACLE ASSEMBLIES	
A	V06-0065	DAI	01/25/06	0° ±2'		.X ±.3	scale 1:1	dwg no	
B	V06-0112	DAI	02/06/06	dr		.XX ±.10		sheet 1 of 2	
C	V07-0276	DAI	2007-04-05	engr		.XXX ±.050		10061262	
				chr				A4	
				appd				type	
								CUSTOMER Drawing	
sheet	revision	c	c						
index	sheet	1	2						

PRODUCT NUMBER

10061262-001LF

NOTES:

1. MATERIAL:

HOUSING: LCP

CONTACT: COPPER ALLOY

CONTACT PLATING: 38 μ m (15 μ in) Au OVER Ni

SOLDER BALL PLATING: SnAgCu

BACKER BOARD: G-10

FLEX CIRCUIT: Polyimide

2. SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE
DUE TO REFLOW ATTACHEMENT.

3. LEAD FREE PRODUCT MEET EUROPEAN UNION DIRECTIVES AND
OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.

4. FOR PROPER APPLICATION, FOLLOW FCI APPLICATION
SPECIFICATION GS-20-033.

5. CONSTRUCTION PER IPC-6013 CLASS II TYPE 3 OR 4.

6. MEG-ARRAY PRODUCT SPECIFICATION: GS-12-100.

Cover coat

 $\frac{1}{2}$ OZ Copper

Adhesive

Polyimide

.81/.84

mat'l. code				surface	tolerance	projection	product family		
SEE NOTES				ASME Y14.5	ASME Y14.5		title		
ltr	ec	no	dr	date	tolerances unless otherwise specified	MM	FLEX CIRCUIT W/240 POS. MEG-ARRAY		
c					angle to line .X $\pm$.3	scale 1:1	RECEPTACLE ASSEMBLIES		
					.XX $\pm$.10		dwg no		
					.XXX $\pm$.050		sheet 2 of		size
				dr	D.INGRAM 01/25/06		10061262		A4
				engr	D.BRANN 01/25/06		type		
				chr	D.BRANN 01/25/06		CUSTOMER Drawing		
				appd	D.BRANN 01/25/06				
sheet index	revision sheet								